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Intel® Core™ i3-6100E Processor (3M Cache, 2.70 GHz)

Specifications Essentials Performance **Memory Specifications Graphics Specifications Expansion Options** Package Specifications Advanced Technologies Intel® Data Protection Technology Intel® Platform Protection Technology

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Specifications Essentials Status Launched Q4'15 Launch Date Processor Number i3-6100E 3 MB SmartCache Cache Bus Speed 8 GT/s DMI3 Instruction Set 64-bit Instruction Set Extensions SSE4.1/4.2, AVX 2.0 Embedded Options Available Q Yes 14 nm Lithography Recommended Customer Price \$225.00 Yes Conflict Free Link Datasheet

Performance 2 # of Cores 4 # of Threads Processor Base Frequency 2.7 GHz 35 W TDP Memory Specifications

Max Memory Size (dependent on memory type) 64 GB DDR4-2133, LPDDR3-1866, Memory Types DDR3L-1600 2 Max # of Memory Channels Max Memory Bandwidth 34.1 GB/s Q Yes ECC Memory Supported # **Graphics Specifications**

Processor Graphics # Intel® HD Graphics 530 350 MHz Graphics Base Frequency Graphics Max Dynamic Frequency 950 MHz Graphics Video Max Memory 64 GB eDP/DP/HDMI/DVI Graphics Output Yes, at 60Hz 4K Support Max Resolution (Intel® WiDi)‡ 1080p 4096x2304@24Hz Max Resolution (HDMI 1.4)‡ Max Resolution (DP)‡ 4096x2304@60Hz Max Resolution (eDP - Integrated Flat Panel)‡ 4096x2304@60Hz N/A Max Resolution (VGA)‡ 12 DirectX* Support OpenGL* Support 4.4 Intel® Quick Sync Video Q Yes Yes Intel® InTru® 3D Technology Intel® Insider™ Yes Q Yes Intel® Wireless Display Intel® Clear Video HD Technology Yes Intel® Clear Video Technology Yes 3 # of Displays Supported # 0x191B Device ID

PCI Express Revision 3.0 PCI Express Configurations # Up to 1x16, 2x8, 1x8+2x4 Max # of PCI Express Lanes 16 Package Specifications Max CPU Configuration 1

Expansion Options

100°C TJUNGTION Package Size 42mm x 28mm Graphics and IMC Lithography 14 nm Sockets Supported FCBGA1440 Low Halogen Options Available See MDDS Advanced Technologies

Intel® Turbo Boost Technology # No Q No Intel® vPro Technology ‡ Q Yes Intel® Hyper-Threading Technology # Intel® Virtualization Technology (VT-x) # Yes Intel® Virtualization Technology for Directed I/O Yes Q (VT-d) # Intel® VT-x with Extended Page Tables (EPT) # Q Yes Intel® TSX-NI Yes Q Yes Intel® 64 # Idle States Yes Enhanced Intel SpeedStep® Technology Q Yes Thermal Monitoring Technologies Yes Yes Intel® Identity Protection Technology # Intel® Data Protection Technology Q Yes Intel® AES New Instructions

Secure Key Yes Intel® Software Guard Extensions (Intel® SGX) Yes Intel® Memory Protection Extensions (Intel® MPX) Yes Intel® Platform Protection Technology OS Guard Yes Trusted Execution Technology # Execute Disable Bit # Yes

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All information provided is subject to change at any time, without notice. Intel may make changes to manufacturing life cycle, specifications, and product descriptions at any time, without notice. The information

Refer to Datasheet for formal definitions of product properties and features. "Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

any item at the time of export.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIO5 that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications [motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIO5, drivers, virtual machine monitor-VMM, platform software, and for operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration. *Conflict free" and *conflict-free" means *DRC conflict free", which is defined by the U.5. Securities and Exchange Commission rules to mean products that do not contain conflict minerals [tin, tantalum, tungsten]

and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo [DRC] or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any

additional included accessories, such as heatsinks/coolers. See http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading-threading-thr processors support Intel® HT Technology.

The Recommended Customer Price [*RCP"] is pricing guidance for Intel products. Prices are for direct Intel customers, typically represent 1,000-unit purchase quantities, and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. If sold in bulk, price represents individual unit. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

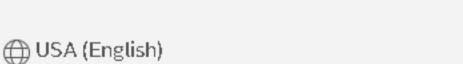
Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology. See www.intel.com/technology/turboboost/ for more information.

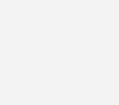
System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used. Low Halogen: Applies only to brominated and chlorinated flame retardants [BFRs/CFRs] and PVC in the final product. Intel components as well as purchased components on the finished assembly meet J5-709.

requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and for PVC may not be better for the environment. For benchmarking data see http://www.intel.com/performance. Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See http://www.intel.com/content

/www/us/en/processors/processor-numbers.html for details. Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.

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